

PURPOSE: To provide a technical condensation of information of interest to electronic device failure analysis technicians, engineers, and managers.

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A TRIBUTE TO LARRY WAGNER

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It is my pleasure and privilege to recognize one of the founders of what EDFAS has been and has become.

Lawrence C. Wagner, FASM, will be leaving the EDFAS Editorial Board with this issue, and the rest of the board thought his contributions should be celebrated. Larry has been a member of the EDFAS board since its inception in 1998, but he has meant so much more to EDFAS and to *EDFA* magazine.

Larry was the first president of EDFAS with its founding in 1998. He later became the first EDFAS member to serve as an ASM trustee. He was also the first EDFAS member to become president of ASM and the first EDFAS member to become an ASM Fellow. Back in 1998, he was the first editor of *Electronic Device Failure Analysis News (EDFAN)*. *EDFAN* was a two-color, 32-page quarterly newsletter serving the EDFAS community and was the predecessor to *EDFA* magazine. Larry has served on the editorial board since 1998 and now after 20 years—at the completion of 20 volumes—is stepping down.



Larry Wagner helps guide discussions at an ASM strategic planning session in Seattle in 2006.

Larry was the lead editor in the early stages and he organized and led a four-person editorial board. As with much of his EDFAS volunteerism, the newsletter was a concept Larry was able to shepherd from a vision to a reality. He was always looking forward. He let that early board know that it was straightforward to produce three to four issues of a newsletter. The challenge was keeping content flowing for the next year, and the next year, and the year after that. This kind of continuity comes from leaders who are willing to make

long-term commitments. Larry's 20 years with the publication shows what leading by example is all about.

A reader survey in the early years showed that the EDFAS community wanted a broader range of content including case histories, conference information, diversity of articles, and other FA resources. As the newsletter grew in content, a decision was made in 2002 to move to a magazine format with a two-color interior and four-color covers. The business case for the jump had to be vetted with both EDFAS and ASM. This was not easy, but Larry stewarded a successful transition.

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GUEST EDITORIAL

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Another reason for the switch from a newsletter to magazine format was the desire of more advertisers to get their messages in front of EDFAS members. Advertising provides value in communicating marketing messages to readers and yields financial advantages to the publication. Larry had the foresight to know there should be a healthy balance between advertising and technical content. Still today in editorial board meetings, an occasional reference is made to the “Wagner Rule” of suggested advertising/editorial percentages.

After stepping down as editor in 2002, Larry remained an active mentor to his successive editors and the entire

editorial board. And characteristic of Larry, he continues to lead by example. Note that Larry compiled the “Product News” department in every single issue until his retirement from the editorial board.

EDFAS and *EDFA* magazine owe much of their success and future to a few hardworking individuals, especially Larry Wagner. We would be remiss if we did not remember that our Society is built on its volunteer members. Larry is one whose exceptional service spans all of EDFAS. It is with gratitude to a personal mentor and friend that I, the editorial board, EDFAS, and all of the extended failure analysis community say “Thank you, Larry.” ■



NOTEWORTHY NEWS

2019 IRPS CONFERENCE

The IEEE International Reliability Physics Symposium’s (IRPS) annual conference will be held **March 31 to April 4** at the Hyatt Regency in Monterey, Calif.

The IRPS technical program includes technical sessions, keynotes and invited talks on emerging issues, tutorials, workshops, poster sessions, a year-in-review seminar, and equipment demonstrations. Special attention is given to the reliability of advanced CMOS scaling, new materials introduction, new processes or integration strategies, and/or fundamentally new device architectures. Attendees returning from IRPS will be better equipped to solve critical reliability problems and develop effective qualification procedures that affect their company’s bottom line.

The IRPS Conference is sponsored by the IEEE Reliability Society and IEEE Electron Devices Society. The 2019 event will be held jointly with the International Electrostatic Discharge Workshop (IEW). For more information, visit the IRPS website at irps.org. ■



2019 FIB SEM MEETING

The 12th annual FIB SEM Meeting will be held **May 6-7** at George Washington University in Washington, D.C. It will feature presentations, tutorials, and posters by FIB users and vendors, highlighting new applications and the latest technology. The event offers plenty of technical content as well as opportunities for informal discussions with your FIB colleagues.

For more information, visit fibsem.net or email keana.scott@nist.gov. ■



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